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ABSTRACT OF THE DISCLOSURE

A semiconductor device having a semiconductor chip,
a wiring board joined to one surface of the semiconductor
chip and electrically connected to the semiconductor
5 chip, and a warp preventing board joined to the other
surface of the semiconductor chip and composed of the same
material as that of the wiring board. An external
connection member for surface mounting may be arranged on
a surface, facing away from the semiconductor chip, of the
10 wiring board.